



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2017-05-31
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Giuseppe Vitali Palma	Representative Title	ADG MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	R1ER*OD0BR52	A	3068	2017-05-31
Amount	UoM	Unit type	ST ECOPACK Grade	
76.00	mg	Each	ECOPACK2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NA	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFN	5-6-0.8	12	Flat	
Comment	PACKAGE: POWER FLAT 5X6 8L SINGLE. MD VALID FOR STL40N10F7, LNK1			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

Query : California Prop65 list, dated 27th January 2017			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.04	Die back side metal - Leadframe metal	513
Lead	2.21	Soft solder	29092

QueryList : REACH-12th January 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	R1ER*OD08R52									
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)				
Die	Other inorganic materials	1.762	mg	supplier	die	Silicon (Si)	7440-21-3		1.689	mg	958570	22224				
				supplier	metallization	Aluminium (Al)	7429-90-5		0.022	mg	12486	289				
				supplier	metallization	Titanium (Ti)	7440-32-6		0.004	mg	2269	53				
				supplier	Passivation	Silicon Oxide	7631-86-9		0.025	mg	14188	329				
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.001	mg	568	13				
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.014	mg	7946	184				
				supplier	back side metallization	Vanadium (V)	7440-62-2		0.001	mg	568	13				
				supplier	back side metallization	Silver (Ag)	7440-22-4		0.006	mg	3405	79				
				Leadframe	Copper & its alloys	49.761	mg	supplier	alloy	Copper (Cu)	7440-50-8		47.784	mg	960270	628737
								supplier	alloy	Iron (Fe)	7439-89-6		1.124	mg	22588	14789
supplier	alloy	Iron Phosphide (FeP)	26508-33-8						0.068	mg	1367	895				
supplier	alloy	Zinc (Zn)	7440-66-6						0.059	mg	1186	776				
supplier	metallization	Nickel (Ni)	7440-02-0						0.025	mg	502	329				
supplier	metallization	Silver (Ag)	7440-22-4						0.699	mg	14047	9197				
supplier	metallization	Phosphorus (P)	12185-10-3						0.002	mg	40	26				
Soft solder	Solder	2.315	mg					JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high met	2.211	mg	955076	29092
				supplier	solder	Silver (Ag)	7440-22-4		0.058	mg	25054	763				
				supplier	solder	Tin (Sn)	7440-31-5		0.046	mg	19870	605				
				supplier	wire	Aluminium (Al)	7429-90-5		0.037	mg	1000000	487				
Bondin wires	Other inorganic materials	0.037	mg	supplier	wire	Aluminium (Al)	7429-90-5		0.037	mg	1000000	487				
				supplier	Ribbon	Aluminium (Al)	7429-90-5		0.321	mg	1000000	4224				
Bonding Ribbons	Other Nonferrous metals & alloys	0.321	mg	supplier	Ribbon	Aluminium (Al)	7429-90-5		0.321	mg	1000000	4224				
				supplier	mold compound	Silica, vitreous	60676-86-0		20.052	mg	925976	263842				
				supplier	mold compound	epoxy resin	85954-11-6		0.866	mg	39990	11395				
				supplier	mold compound	phenol resin	26834-02-6		0.650	mg	30016	8553				
Encapsulation	Other Organic Materials	21.655	mg	supplier	mold compound	carbon black	1333-86-4		0.087	mg	4018	1145				
				supplier	mold compound	carbon black	1333-86-4		0.087	mg	4018	1145				
Connections coating	Solder	0.149	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		0.149	mg	1000000	1961				